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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/537,286	06/01/2005	Masashi Gotoh	273043US3PCT	1853
22850 7590 04/09/2007 OBLON, SPIVAK, MCCLELLAND, MAIER & NEUSTADT, P.C. 1940 DUKE STREET ALEXANDRIA, VA 22314			EXAMINER HARRISON, MONICA D	
			ART UNIT	PAPER NUMBER
			2813	
SHORTENED STATUTORY PERIOD OF RESPONSE		NOTIFICATION DATE	DELIVERY MODE	
3 MONTHS		04/09/2007	ELECTRONIC	

**Please find below and/or attached an Office communication concerning this application or proceeding.**

If NO period for reply is specified above, the maximum statutory period will apply and will expire 6 MONTHS from the mailing date of this communication.

Notice of this Office communication was sent electronically on the above-indicated "Notification Date" and has a shortened statutory period for reply of 3 MONTHS from 04/09/2007.

Notice of the Office communication was sent electronically on above-indicated "Notification Date" to the following e-mail address(es):

patentdocket@oblon.com  
oblonpat@oblon.com  
jgardner@oblon.com

TH

**Office Action Summary**

Application No.

10/537,286

Applicant(s)

GOTOH ET AL.

Examiner

Monica D. Harrison

Art Unit

2813

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

**Period for Reply**

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) OR THIRTY (30) DAYS, WHICHEVER IS LONGER, FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

**Status**

- 1) ☒ Responsive to communication(s) filed on 29 September 2006.
- 2a) ☒ This action is **FINAL**.                      2b) ☐ This action is non-final.
- 3) ☐ Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

**Disposition of Claims**

- 4) ☒ Claim(s) 10-35 is/are pending in the application.
- 4a) Of the above claim(s) 1-9 is/are withdrawn from consideration.
- 5) ☐ Claim(s) \_\_\_\_\_ is/are allowed.
- 6) ☒ Claim(s) 10-35 is/are rejected.
- 7) ☐ Claim(s) \_\_\_\_\_ is/are objected to.
- 8) ☐ Claim(s) \_\_\_\_\_ are subject to restriction and/or election requirement.

**Application Papers**

- 9) ☐ The specification is objected to by the Examiner.
- 10) ☐ The drawing(s) filed on \_\_\_\_\_ is/are: a) ☐ accepted or b) ☐ objected to by the Examiner.  
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).  
Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).
- 11) ☐ The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

**Priority under 35 U.S.C. § 119**

- 12) ☐ Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
- a) ☐ All    b) ☐ Some \*    c) ☐ None of:
1. ☐ Certified copies of the priority documents have been received.
  2. ☐ Certified copies of the priority documents have been received in Application No. \_\_\_\_\_.
  3. ☐ Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).

\* See the attached detailed Office action for a list of the certified copies not received.

**Attachment(s)**

- 1) ☒ Notice of References Cited (PTO-892)
- 2) ☐ Notice of Draftsperson's Patent Drawing Review (PTO-948)
- 3) ☐ Information Disclosure Statement(s) (PTO/SB/08)  
Paper No(s)/Mail Date \_\_\_\_\_.

- 4) ☐ Interview Summary (PTO-413)  
Paper No(s)/Mail Date. \_\_\_\_\_.
- 5) ☐ Notice of Informal Patent Application
- 6) ☐ Other: \_\_\_\_\_.

### DETAILED ACTION

1. Applicant's amendment filed 9/29/06 has been entered. Examiner acknowledges claims 1-9 have been cancelled. Newly admitted claims 10-35 have been entered.

#### *Claim Rejections - 35 USC § 103*

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negated by the manner in which the invention was made.

Claims 10-22 are rejected under 35 U.S.C. 103(a) as being unpatentable over Kitamura et al (5,480,048) in view of Banks et al (5,970,319).

2. Regarding claim 10, Kitamura et al discloses a method for manufacturing an electronic part in which a layer having a uniform thickness is formed, the method comprising: forming a conductor portion (Figure 1e, references 101 and 102) on a surface of a support member (Figure 1e, reference 100) and bringing an insulating sheet into contact with the conductor portion from above (Figure 1e, reference 107). However, Kitamura et al does not disclose pressing the insulating sheet to a height of the conductor portion using the conductor portion as a stopper to make the height of the insulating sheet equal to the height of the conductor portion.

Banks et al discloses pressing the insulating sheet to a height of the conductor portion using the conductor portion as a stopper to make the height of the insulating sheet equal to the height of the conductor portion (column 4, lines 34-46).

It is obvious, at the time the invention was made, for one having ordinary skill in the art, to modify Kitamura et al with the teachings of Banks et al, for the purpose of making connections within a semiconductor device.

3. Regarding claim 11, Kitamura et al discloses wherein said conductor portion and said insulating sheet are detached from said surface, after making the height of said insulating sheet equal to the height of said conductor portion (Figure 1e).

4. Regarding claim 12, Kitamura et al discloses wherein said support member is a substrate of said electronic part (Figure 1e, reference 100).

5. Regarding claim 13, Kitamura et al discloses wherein a B-stage sheet is used as said insulating sheet (Figure 15A, reference 1504).

6. Regarding claim 14, Kitamura et al discloses wherein a B-stage sheet is used as said insulating sheet (Figure 15A, reference 1504).

7. Regarding claim 15, Kitamura et al discloses wherein a thermoplastic insulating sheet is used as said insulating sheet (Figure 1e, reference 107).

8. Regarding claim 16, Kitamura et al discloses wherein a thermoplastic insulating sheet is used as said insulating sheet (Figure 1e, reference 107).

9. Regarding claims 17-22, Kitamura et al discloses wherein heating is performed in addition to said pressing (column 31, lines 10-20)

Claims 23-35 are rejected under 35 U.S.C. 103(a) as being unpatentable over Kitamura et al (5,480,048) in view of Banks et al (5,970,319).

10. Regarding claim 23, Kitamura et al discloses a method for manufacturing an electronic part in which a layer having a uniform thickness is formed, the method comprising:

Art Unit: 2813

forming a power supply film (Figure 14, reference 1405) on a surface of a support member (Figure 14, reference 1401); forming a conductor portion by plating using the power supply film as an electrode (Figure 14, reference 1402) and bringing an insulating sheet into contact with the conductor portion from above (Figure 14, reference 1406)(column 1, lines 29-55). However, Kitamura et al does not disclose pressing the insulating sheet to the height of the conductor portion using said conductor portion.

Banks et al discloses pressing the insulating sheet to a height of the conductor portion using the conductor portion (column 4, lines 34-46).

It is obvious, at the time the invention was made, for one having ordinary skill in the art, to modify Kitamura et al with the teachings of Banks et al, for the purpose of making connections within a semiconductor device.

11. Regarding claim 24, Kitamura et al discloses wherein said conductor portion and said insulating sheet are detached from said surface, after making the height of said insulating sheet equal to the height of said conductor portion (Figure 1e).

12. Regarding claim 25, Kitamura et al discloses wherein said support member is a substrate of said electronic part (Figure 1e, reference 100).

13. Regarding claim 26, Kitamura et al discloses wherein a B-stage sheet is used as said insulating sheet (Figure 15A, reference 1504).

14. Regarding claim 27, Kitamura et al discloses wherein a B-stage sheet is used as said insulating sheet (Figure 15A, reference 1504).

15. Regarding claim 28, Kitamura et al discloses wherein a thermoplastic insulating sheet is used as said insulating sheet (Figure 1e, reference 107).

16. Regarding claim 29, Kitamura et al discloses wherein a thermoplastic insulating sheet is used as said insulating sheet (Figure 1e, reference 107).

17. Regarding claims 30-35, Kitamura et al discloses wherein heating is performed in addition to said pressing (column 31, lines 10-20).

***Conclusion***

18. Applicant's amendment necessitated the new ground(s) of rejection presented in this Office action. Accordingly, **THIS ACTION IS MADE FINAL**. See MPEP § 706.07(a). Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the date of this final action.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Monica D. Harrison whose telephone number is 571-272-1959. The examiner can normally be reached on M-F 7:00am-3:30pm.

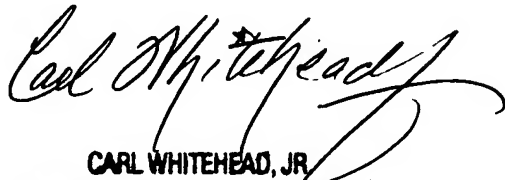
If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Carl Whitehead Jr. can be reached on 571-272-1702. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Art Unit: 2813

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free). If you would like assistance from a USPTO Customer Service Representative or access to the automated information system, call 800-786-9199 (IN USA OR CANADA) or 571-272-1000.

Monica D. Harrison  
AU 2813

mdh  
April 2, 2007

  
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